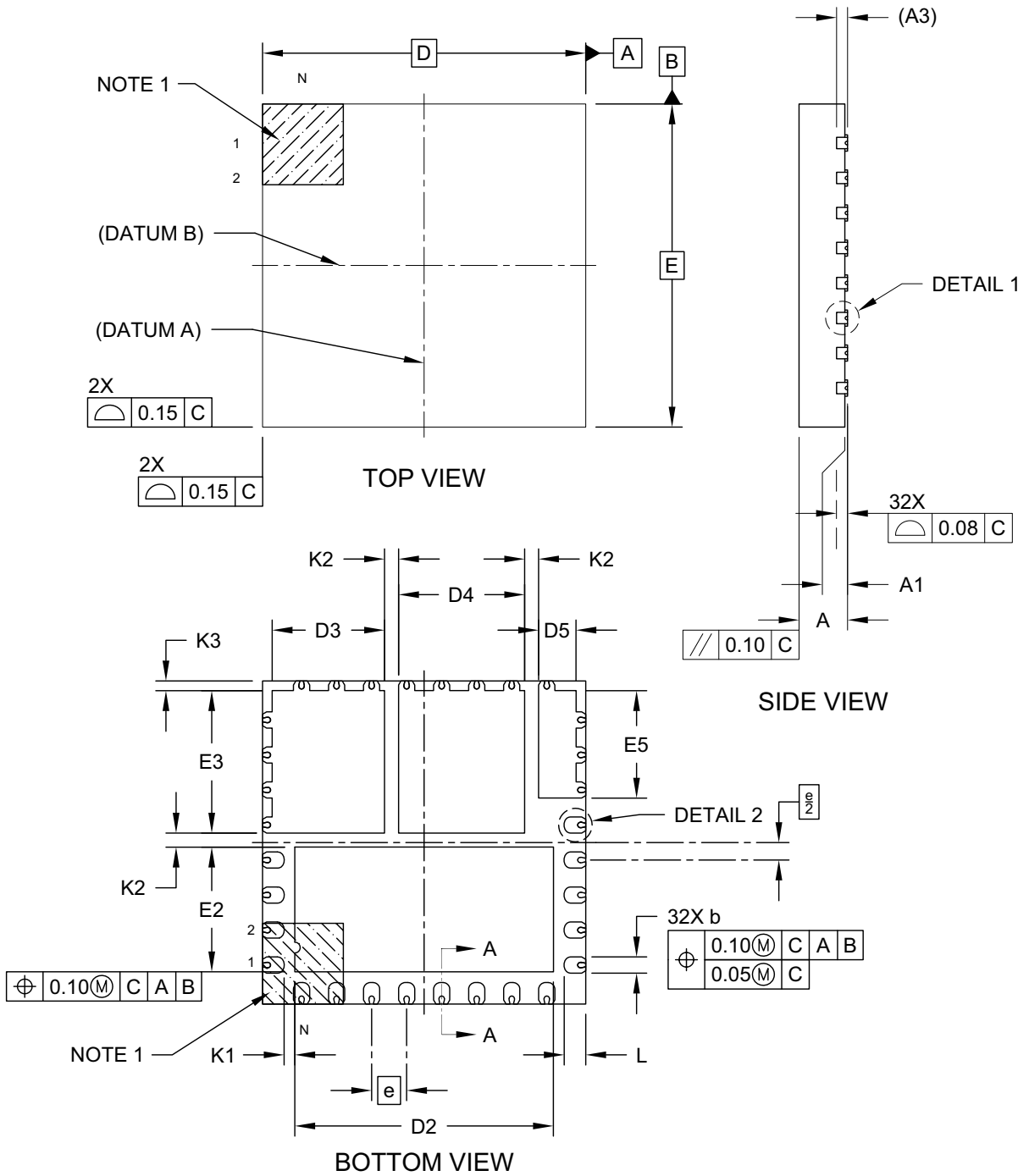


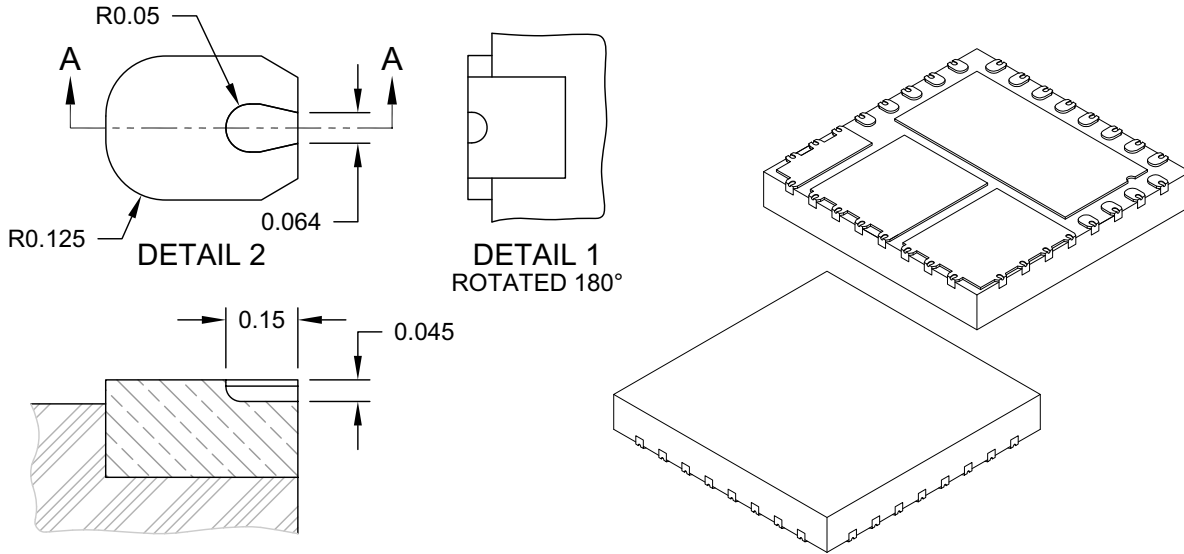
**32-Lead Very Thin Plastic Quad Flat, No Lead Package (PHA) - 6x6 mm Body [VQFN]  
Wettable Flanks, Multiple Exposed Pads**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



**32-Lead Very Thin Plastic Quad Flat, No Lead Package (PHA) - 6x6 mm Body [VQFN]  
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SECTION A-A

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	32		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.203 REF		
Overall Length	D	6.00 BSC		
Overall Width	E	6.00 BSC		
Exposed Pad Length	D2	4.70	4.80	4.90
Exposed Pad Width	E2	2.215	2.315	2.415
Exposed Pad Length	D3	1.985	2.085	2.185
Exposed Pad Width	E3	2.545	2.645	2.745
Exposed Pad Length	D4	2.240	2.340	2.440
Exposed Pad Length	D5	0.595	0.695	0.795
Exposed Pad Width	E5	1.895	1.995	2.095
Terminal Width	b	0.25	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed Pad	K1	0.20	-	-
Exposed Pad-to-Exposed Pad	K2	0.20	0.26	-
Package Edge-to-Exposed Pad	K3	0.18	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1196C Sheet 2 of 2

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